TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (L^2 - π -MOSV)

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High Speed Switching Applications Switching Regulator, DC-DC Converter and Motor Drive Applications

- 4 V gate drive
- Low drain-source ON resistance: R_{DS} (ON) = 0.08 Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 17 \text{ S}$ (typ.)
- Low leakage current: $IDSS = 100 \mu A (VDS = 150 V)$
- Enhancement-mode: $V_{th} = 0.8 \sim 2.0 \text{ V} (V_{DS} = 10 \text{ V}, \text{ Ip} = 1 \text{ mA})$

Maximum Ratings (Tc = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	150	V	
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V _{DGR}	150	V	
Gate-source voltage		V _{GSS}	±20	V	
Drain current	DC	Ι _D	18	А	
	Pulse	I _{DP}	54	A	
Drain power dissipation (Tc = 25°C)		PD	100	W	
Single pulse avalanche energy**		E _{AS}	176	mJ	
Repetitive avalanche energy*		E _{AR}	10	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	



Notice: S1: Input signal pin S2: Source current

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Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	1.25	°C/W

Note1:

Repetitive rating; pulse width limited by max junction temperature.

** V_{DD} = 50 V, T_{ch} = 25°C (initial), L = 800 μH, R_G = 25 Ω, I_{AR} = 18 A

This transistor is an electrostatic sensitive device. Please handle with caution.



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Electrical Characteristics (Note2) (Tc = 25°C)

Char	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rent	I _{GSS}	$V_{GS} = \pm 16 \text{ V}, \text{ V}_{DS} = 0 \text{ V}$	_	_	±10	μA
Drain cut-off current		I _{DSS}	$V_{DS} = 150 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$		_	100	μA
Drain-source bre	akdown voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	150	_	_	V
Gate threshold v	oltage	V _{th}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$	0.8	_	2.0	V
Drain-source ON resistance		R _{DS (ON)}	$V_{GS} = 4 V$, $I_D = 9 A$		0.09	0.18	Ω
			$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 9 \text{ A}$	_	0.08	0.12	
Forward transfer	admittance	Y _{fs}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 9 \text{ A}$	10	17		S
Input capacitance		C _{iss}			1380	_	pF
Reverse transfer capacitance		C _{rss}	$V_{DS} = 10 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$		200		рF
Output capacitance		C _{oss}			610		pF
Switching time	Rise time	tr	$V_{GS1}^{10 V}$ $U_{GS1}^{10 V}$ $G \circ D$ $G \circ C$ $R_{L} = 11 \Omega$ $S_{10} \circ C$ $S_{20} \circ C$	—	12	—	- ns
	Turn-on time	t _{on}		_	20	_	
	Fall time	t _f			12		
	Turn-off time	t _{off}	$V_{IN}: t_r, t_f < 5 \text{ ns} \qquad \not T \qquad V_{DD} \simeq 100 \text{ V}$ Duty $\leq 1\%, t_W = 10 \mu\text{s}$	_	68	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	57	_	nC
Gate-source charge		Q _{gs}	$V_{DD} \simeq 120 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 18 \text{ A}$	_	43	_	nC
Gate-drain ("miller") charge		Q _{gd}		_	14	_	nC

Note2: Please connect the S1 pin and S2 pin, and then ground the connected pin. (However, while switching times are measured, please don't connect and ground it.)

Source-Drain Diode Ratings and Characteristics (Note3) (Tc = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current ***	I _{DR} 1	_	_	_	18	А
Pulse drain reverse current ***	I _{DRP} 1		_	_	54	А
Continuous drain reverse current ***	I _{DR} 2			_	1	А
Pulse drain reverse current ***	I _{DRP} 2			_	4	А
Diode forward voltage	V _{DS2F}	$I_{DR1} = 18 \text{ A}, V_{GS} = 0 \text{ V}$		_	-1.7	V
Reverse recovery time	t _{rr}	$I_{DR} = 18 \text{ A}, V_{GS} = 0 \text{ V},$	_	185	_	ns
Reverse recovery charge	Q _{rr}	dl _{DR} /dt = 100 A/μs		1.3	_	μC

Note 3:

*** drain, flowing current value between the S2 pin, open the S1 pin drain, flowing current value between the S1 pin, open the S2 pin

Unless otherwise specified, please connect the S1 and S2 pins, and then ground the connected pin.

Marking



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Safe operating area 100 -ID max (pulsed) * 50 100 µs 30 -ID max _(continuous) € 10 Drain current ID +++5 DC operation Tc = 25°C 1 * Single nonrepetitive pulse 0.5 Tc = 25°C 0.3 Curves must be derated linearly with increase in temperature. VDSS max 0.1 3 10 . 1 30 100 300 Drain-source voltage V_{DS} (V)



 $\begin{array}{l} \text{Peak I}_{AR} = 18 \text{ A}, \text{ R}_{G} = 25 \ \Omega \\ \text{V}_{DD} = 50 \text{ V}, \text{ L} = 0.8 \text{ mH} \end{array} \\ \text{E}_{AS} = \frac{1}{2} \cdot \text{L} \cdot \text{I}^{2} \cdot \left(\frac{\text{B}_{VDSS}}{\text{B}_{VDSS} - \text{V}_{DD}} \right) \end{array}$